

Trench gate field-stop IGBT, M series 650 V, 30 A low loss

Datasheet - production data

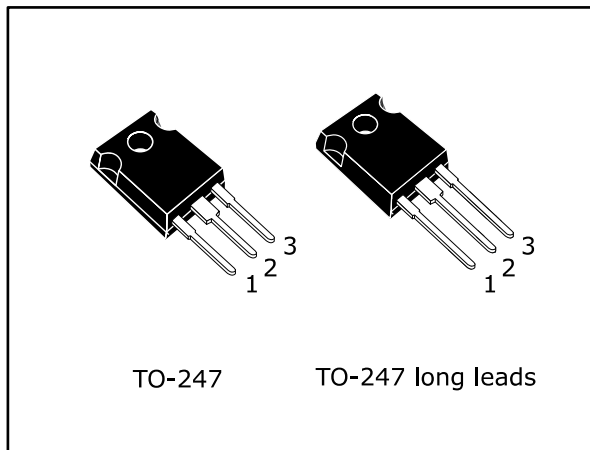
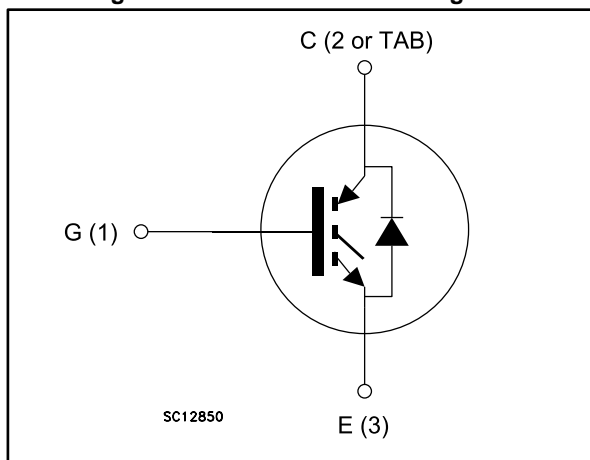


Figure 1: Internal schematic diagram



Features

- 6 μ s of minimum short-circuit withstand time
- $V_{CE(sat)} = 1.55$ V (typ.) @ $I_C = 50$ A
- Tight parameters distribution
- Safer paralleling
- Low thermal resistance
- Soft and very fast recovery antiparallel diode

Applications

- Motor control
- UPS
- PFC

Description plur

These devices are IGBTs developed using an advanced proprietary trench gate field-stop structure. These devices are part of the M series of IGBTs, which represent an optimum compromise in performance to maximize the efficiency of inverter systems where low-loss and short-circuit capability are essential. Furthermore, a positive $V_{CE(sat)}$ temperature coefficient and tight parameter distribution result in safer paralleling operation.

Table 1: Device summary

Order code	Marking	Package	Packaging
STGW30M65DF2	G30M65DF2	TO-247	Tube
STGWA30M65DF2	G30M65DF2	TO-247 long leads	Tube

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage ($V_{GE} = 0$)	650	V
I_C	Continuous collector current at $T_C = 25\text{ °C}$	60	A
I_C	Continuous collector current at $T_C = 100\text{ °C}$	30	A
$I_{CP}^{(1)}$	Pulsed collector current	120	A
V_{GE}	Gate-emitter voltage	± 20	V
I_F	Continuous forward current at $T_C = 25\text{ °C}$	60	A
I_F	Continuous forward current at $T_C = 100\text{ °C}$	30	A
$I_{FP}^{(1)}$	Pulsed forward current	120	A
P_{TOT}	Total dissipation at $T_C = 25\text{ °C}$	258	W
T_{STG}	Storage temperature range	- 55 to 150	°C
T_J	Operating junction temperature	- 55 to 175	°C

Notes:

⁽¹⁾Pulse width limited by maximum junction temperature.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case IGBT	0.58	°C/W
R_{thJC}	Thermal resistance junction-case diode	1.47	°C/W
R_{thJA}	Thermal resistance junction-ambient	50	°C/W

2 Electrical characteristics

$T_C = 25\text{ °C}$ unless otherwise specified

Table 4: Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}$, $I_C = 2\text{ mA}$	650			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}$, $I_C = 30\text{ A}$		1.55	2.0	V
		$V_{GE} = 15\text{ V}$, $I_C = 30\text{ A}$, $T_J = 125\text{ °C}$		1.95		
		$V_{GE} = 15\text{ V}$, $I_C = 30\text{ A}$, $T_J = 175\text{ °C}$		2.1		
V_F	Forward on-voltage	$I_F = 30\text{ A}$		1.85		V
		$I_F = 30\text{ A}$, $T_J = 125\text{ °C}$		1.6		
		$I_F = 30\text{ A}$, $T_J = 175\text{ °C}$		1.5		
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}$, $I_C = 500\text{ }\mu\text{A}$	5	6	7	V
I_{CES}	Collector cut-off current	$V_{GE} = 0\text{ V}$, $V_{CE} = 650\text{ V}$			25	μA
I_{GES}	Gate-emitter leakage current	$V_{CE} = 0\text{ V}$, $V_{GE} = \pm 20\text{ V}$			250	μA

Table 5: Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	$V_{CE} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GE} = 0\text{ V}$	-	2490	-	pF
C_{oes}	Output capacitance		-	143	-	
C_{res}	Reverse transfer capacitance		-	46	-	
Q_g	Total gate charge	$V_{CC} = 520\text{ V}$, $I_C = 30\text{ A}$, $V_{GE} = 15\text{ V}$ (see Figure 30: "Gate charge test circuit")	-	80	-	nC
Q_{ge}	Gate-emitter charge		-	18	-	
Q_{gc}	Gate-collector charge		-	32	-	

Table 6: IGBT switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$, $I_C = 30\text{ A}$, $V_{GE} = 15\text{ V}$, $R_G = 10\ \Omega$ (see Figure 29: "Test circuit for inductive load switching")		31.6	-	ns
t_r	Current rise time			13.4	-	ns
$(di/dt)_{on}$	Turn-on current slope			1791	-	A/ μ s
$t_{d(off)}$	Turn-off-delay time			115	-	ns
t_f	Current fall time			110	-	ns
$E_{on}^{(1)}$	Turn-on switching losses			0.3	-	mJ
$E_{off}^{(2)}$	Turn-off switching losses			0.96	-	mJ
E_{ts}	Total switching losses			1.26	-	mJ
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$, $I_C = 30\text{ A}$, $V_{GE} = 15\text{ V}$, $R_G = 10\ \Omega$, $T_J = 175\text{ }^\circ\text{C}$ (see Figure 29: "Test circuit for inductive load switching")		30	-	ns
t_r	Current rise time			17	-	ns
$(di/dt)_{on}$	Turn-on current slope			1435	-	A/ μ s
$t_{d(off)}$	Turn-off-delay time			116	-	ns
t_f	Current fall time			194	-	ns
E_{on}	Turn-on switching losses			0.67	-	mJ
E_{off}	Turn-off switching losses			1.36	-	mJ
E_{ts}	Total switching losses			2.03	-	mJ
t_{sc}	Short-circuit withstand time	$V_{CC} = 400\text{ V}$, $V_{GE} = 13\text{ V}$, $T_{Jstart} = 150\text{ }^\circ\text{C}$	10		-	μ s
		$V_{CC} = 400\text{ V}$, $V_{GE} = 15\text{ V}$, $T_{Jstart} = 150\text{ }^\circ\text{C}$	6		-	

Notes:

⁽¹⁾Energy losses include reverse recovery of the diode.

⁽²⁾Turn-off losses also include the tail of the collector current.

Table 7: Diode switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$I_F = 30\text{ A}$, $V_R = 400\text{ V}$, $V_{GE} = 15\text{ V}$ (see Figure 29: "Test circuit for inductive load switching") $di/dt = 1000\text{ A}/\mu\text{s}$	-	140		ns
Q_{rr}	Reverse recovery charge		-	880		nC
I_{rrm}	Reverse recovery current		-	17		A
dl_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	650		A/ μs
E_{rr}	Reverse recovery energy		-	115		μJ
t_{rr}	Reverse recovery time	$I_F = 30\text{ A}$, $V_R = 400\text{ V}$, $V_{GE} = 15\text{ V}$ $T_J = 175\text{ }^\circ\text{C}$ (see Figure 29: "Test circuit for inductive load switching") $di/dt = 1000\text{ A}/\mu\text{s}$	-	244		ns
Q_{rr}	Reverse recovery charge		-	2743		nC
I_{rrm}	Reverse recovery current		-	25		A
dl_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	220		A/ μs
E_{rr}	Reverse recovery energy		-	320		μJ

2.1 Electrical characteristics (curves)

2.2

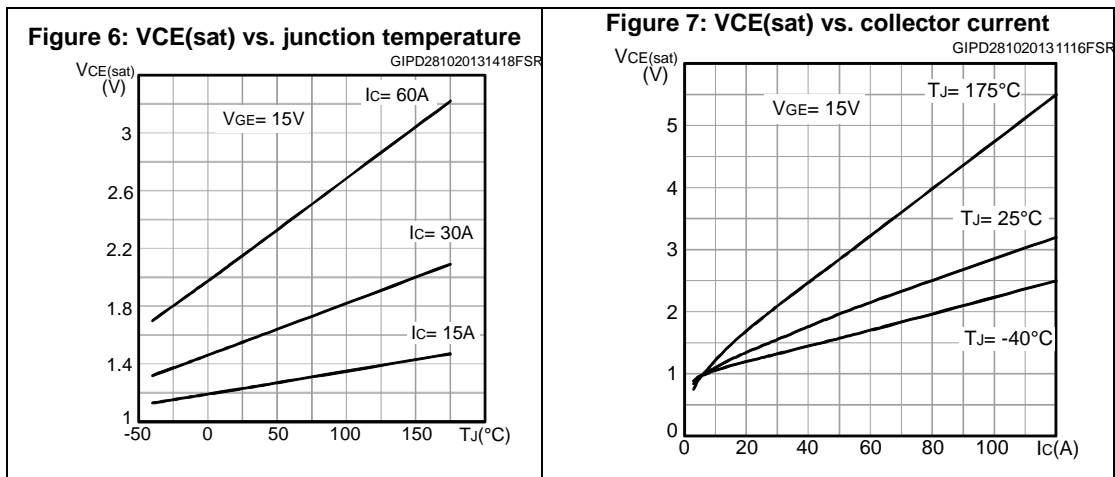
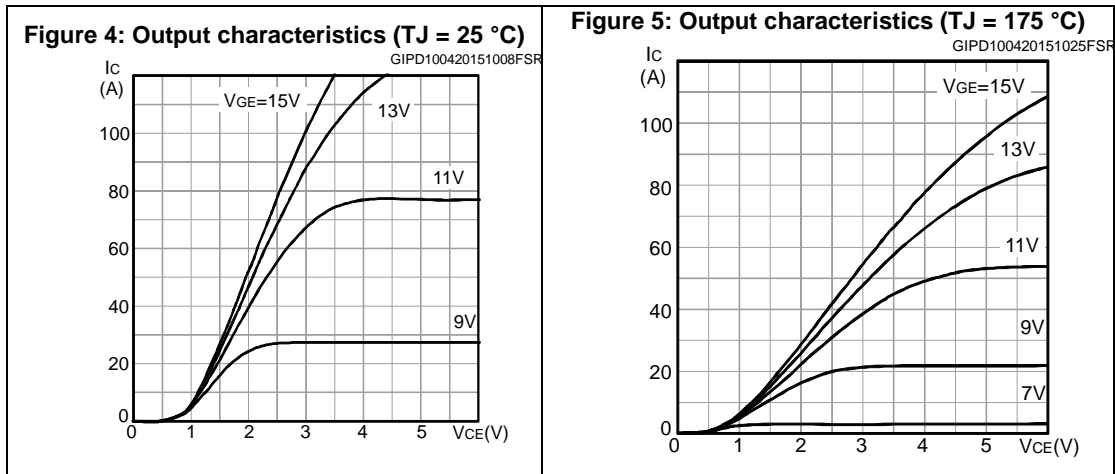
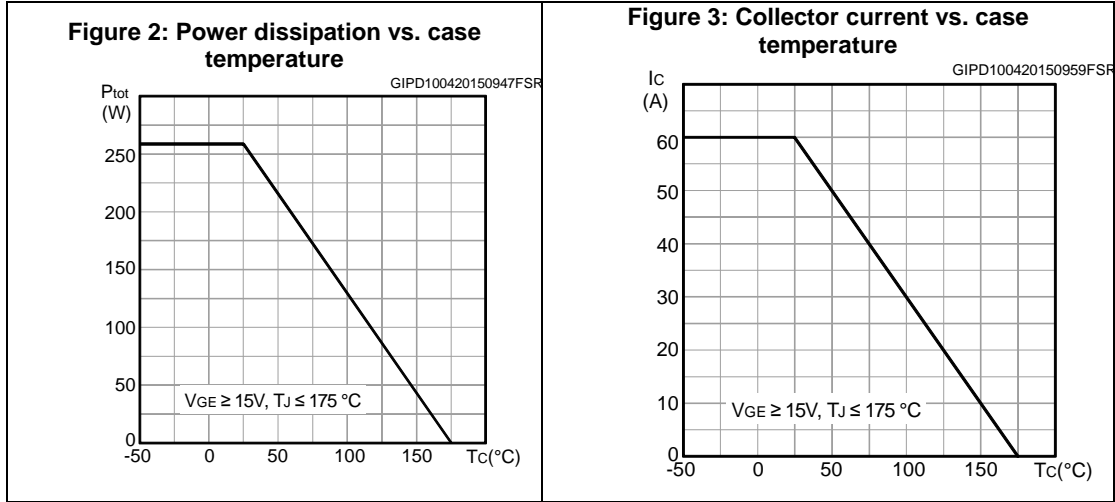


Figure 8: Collector current vs. switching frequency

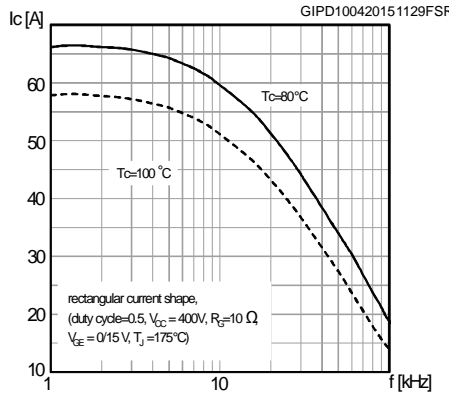


Figure 9: Forward bias safe operating area

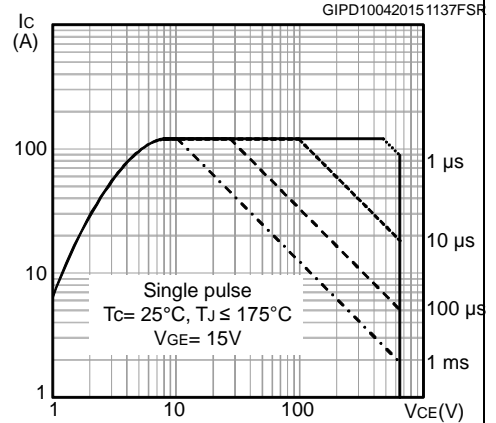


Figure 10: Transfer characteristics

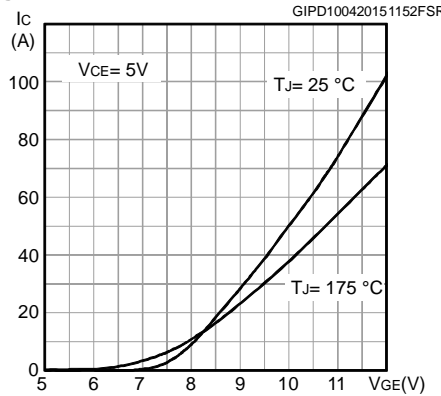


Figure 11: Diode VF vs. forward current

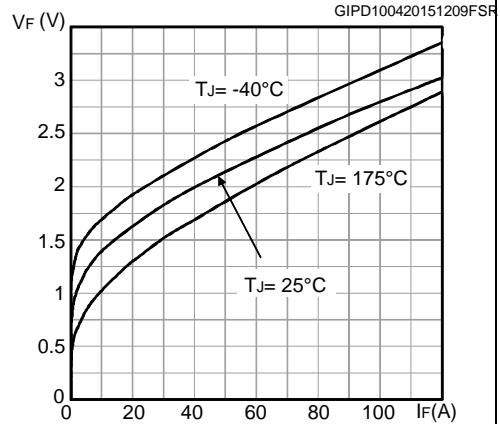


Figure 12: Normalized VGE(th) vs. junction temperature

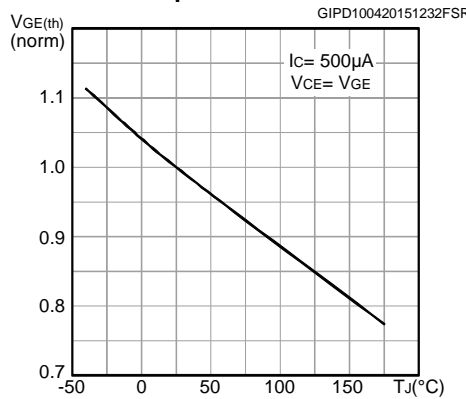


Figure 13: Normalized V(BR)CES vs. junction temperature

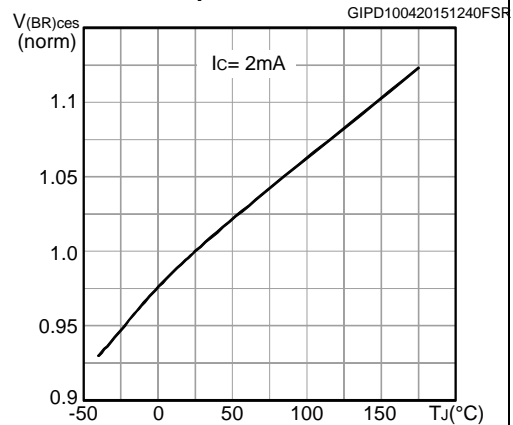


Figure 14: Capacitance variations

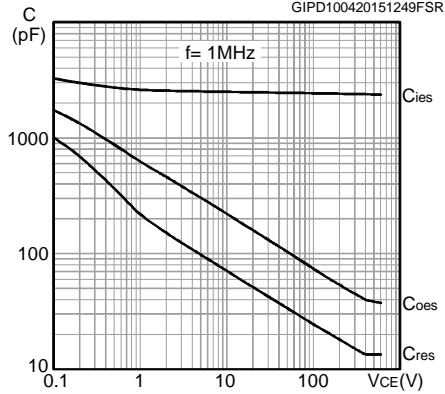


Figure 15: Gate charge vs. gate-emitter voltage

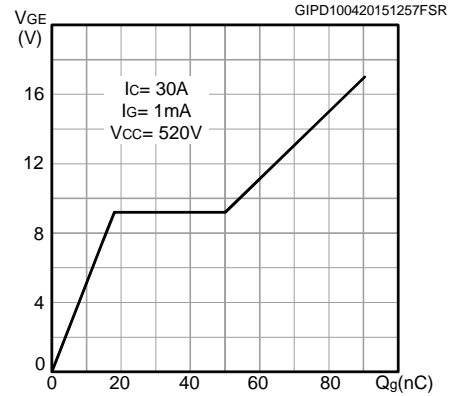


Figure 16: Switching loss vs. collector current

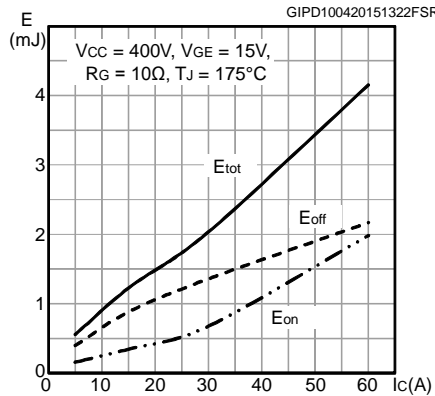


Figure 17: Switching loss vs. gate resistance

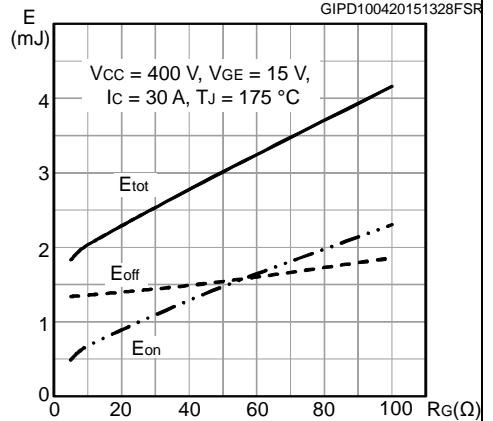


Figure 18: Switching loss vs. temperature

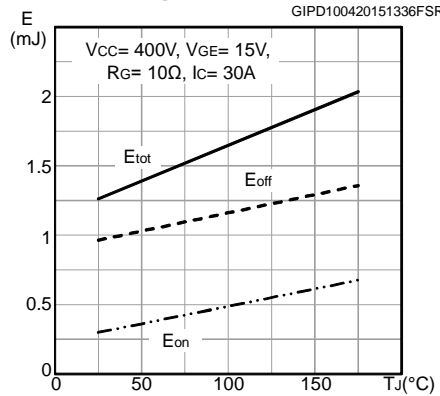
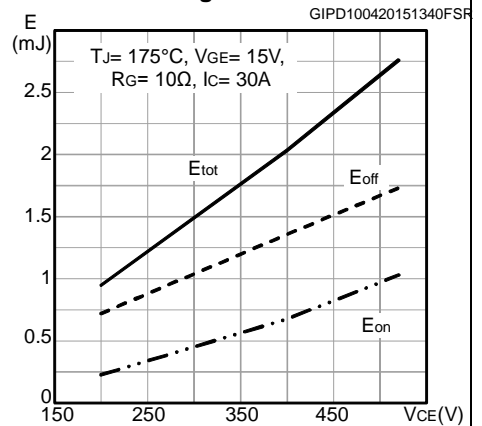


Figure 19: Switching loss vs. collector emitter voltage



Electrical characteristics

STGW30M65DF2, STGWA30M65DF2

Figure 20: Short-circuit time and current vs. VGE

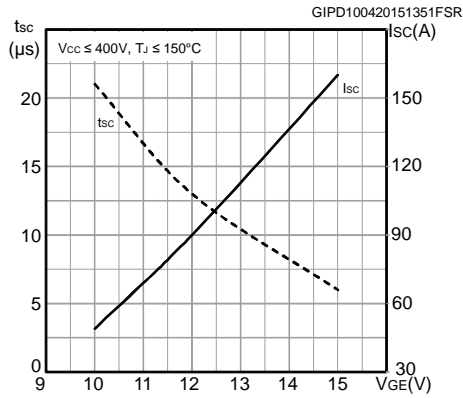


Figure 21: Switching times vs. collector current

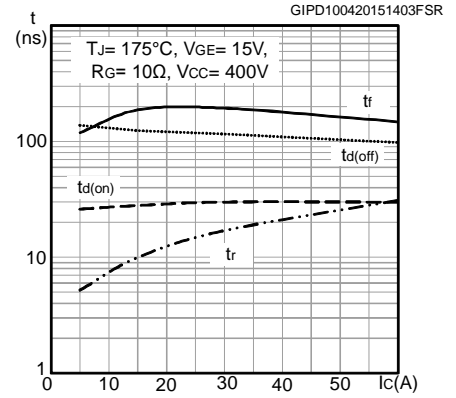


Figure 22: Switching times vs. gate resistance

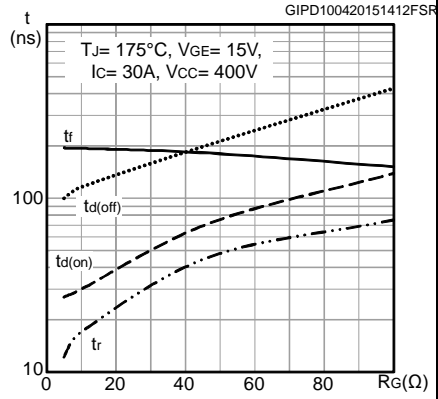


Figure 23: Reverse recovery current vs. diode current slope

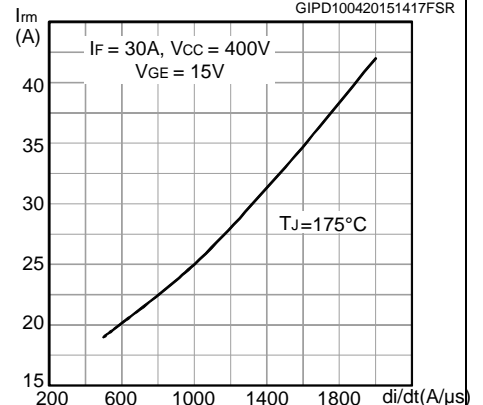


Figure 24: Reverse recovery time vs. diode current slope

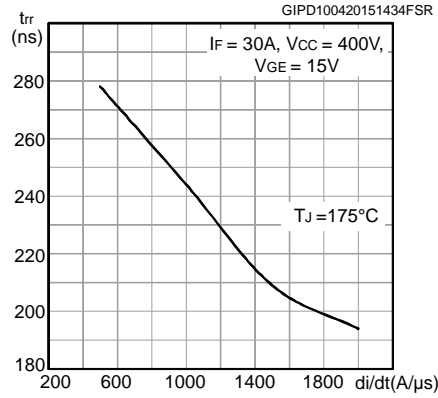


Figure 25: Reverse recovery charge vs. diode current slope

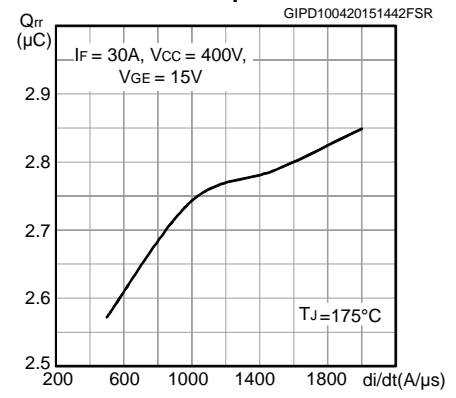


Figure 26: Reverse recovery energy vs. diode current slope

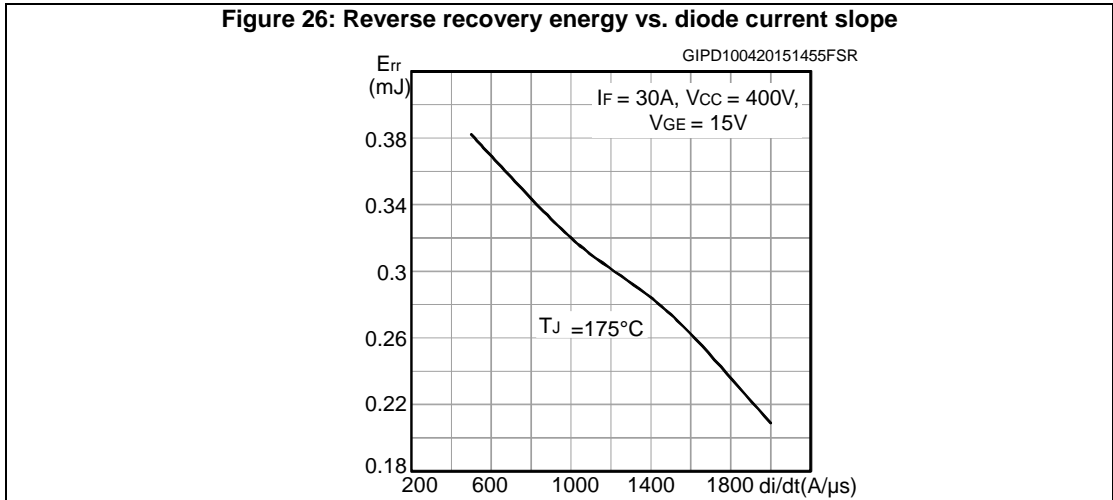


Figure 27: Thermal impedance for IGBT

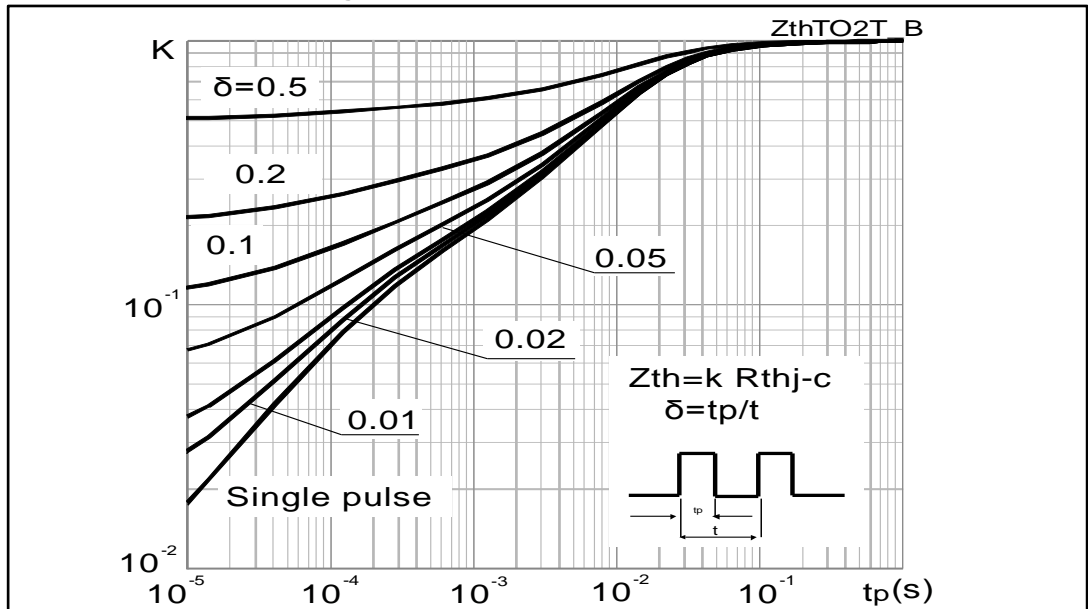
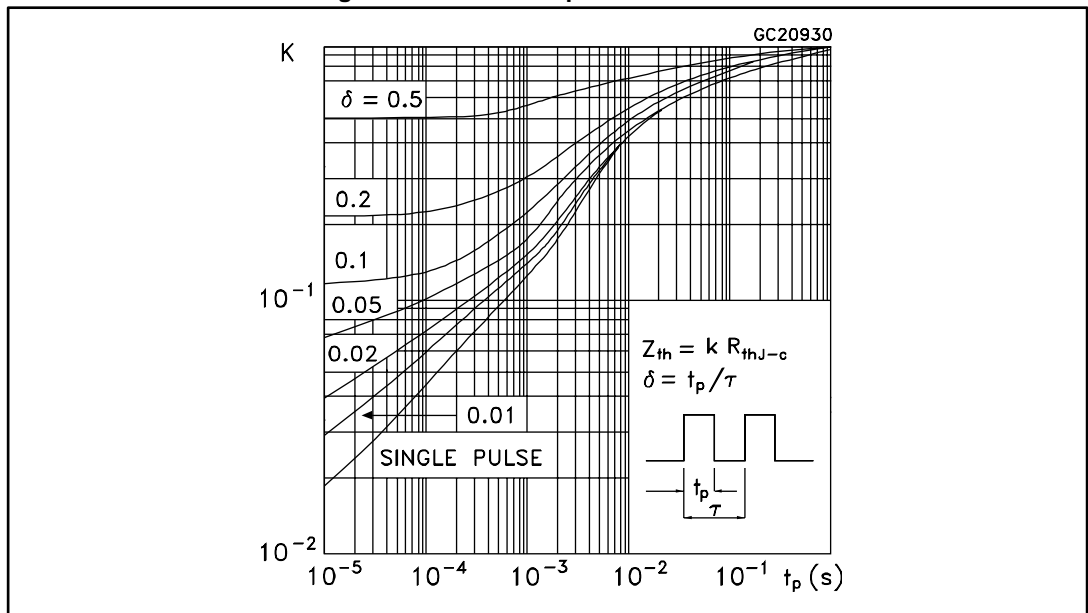
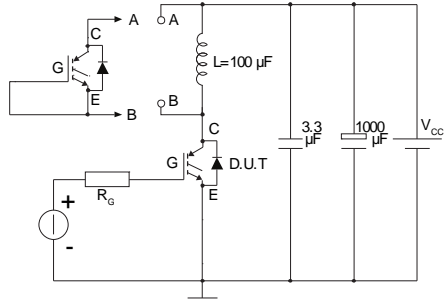


Figure 28: Thermal impedance for diode



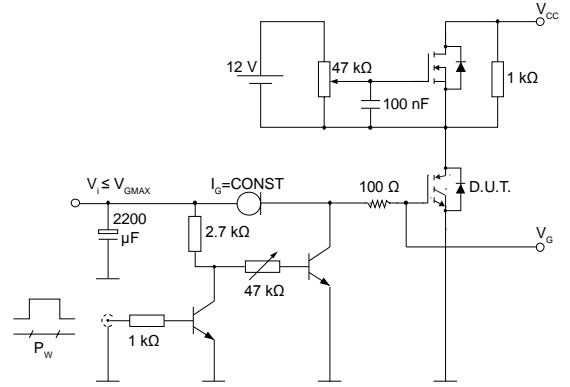
3 Test circuits

Figure 29: Test circuit for inductive load switching



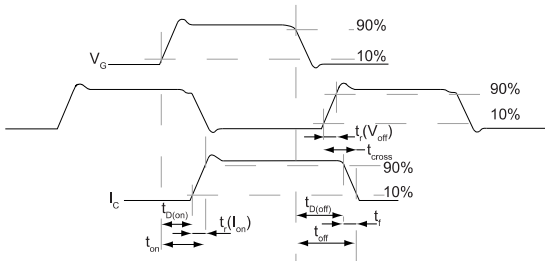
AM01504v1

Figure 30: Gate charge test circuit



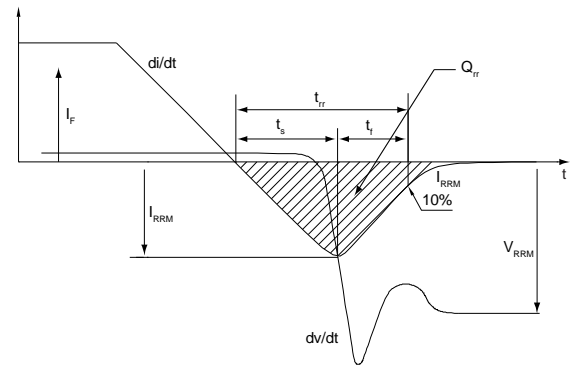
AM01505v1

Figure 31: Switching waveform



AM01506v1

Figure 32: Diode reverse recovery waveform



AM01507v1

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

4.1 TO-247 package information

Figure 33: TO-247 package outline

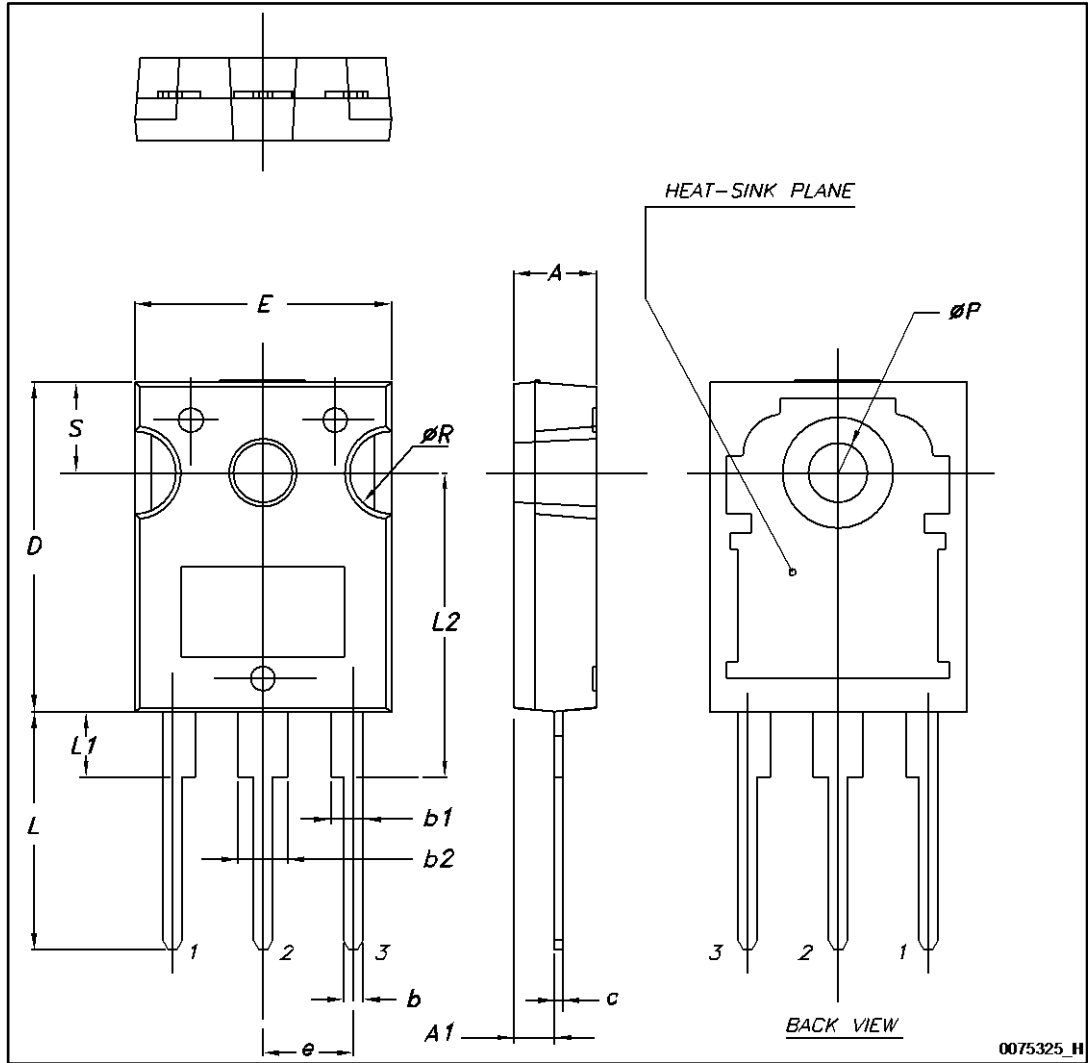


Table 8: TO-247 package mechanical data

Dim.	mm.		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

4.2 TO-247 long leads package information

Figure 34: TO-247 long leads package outline

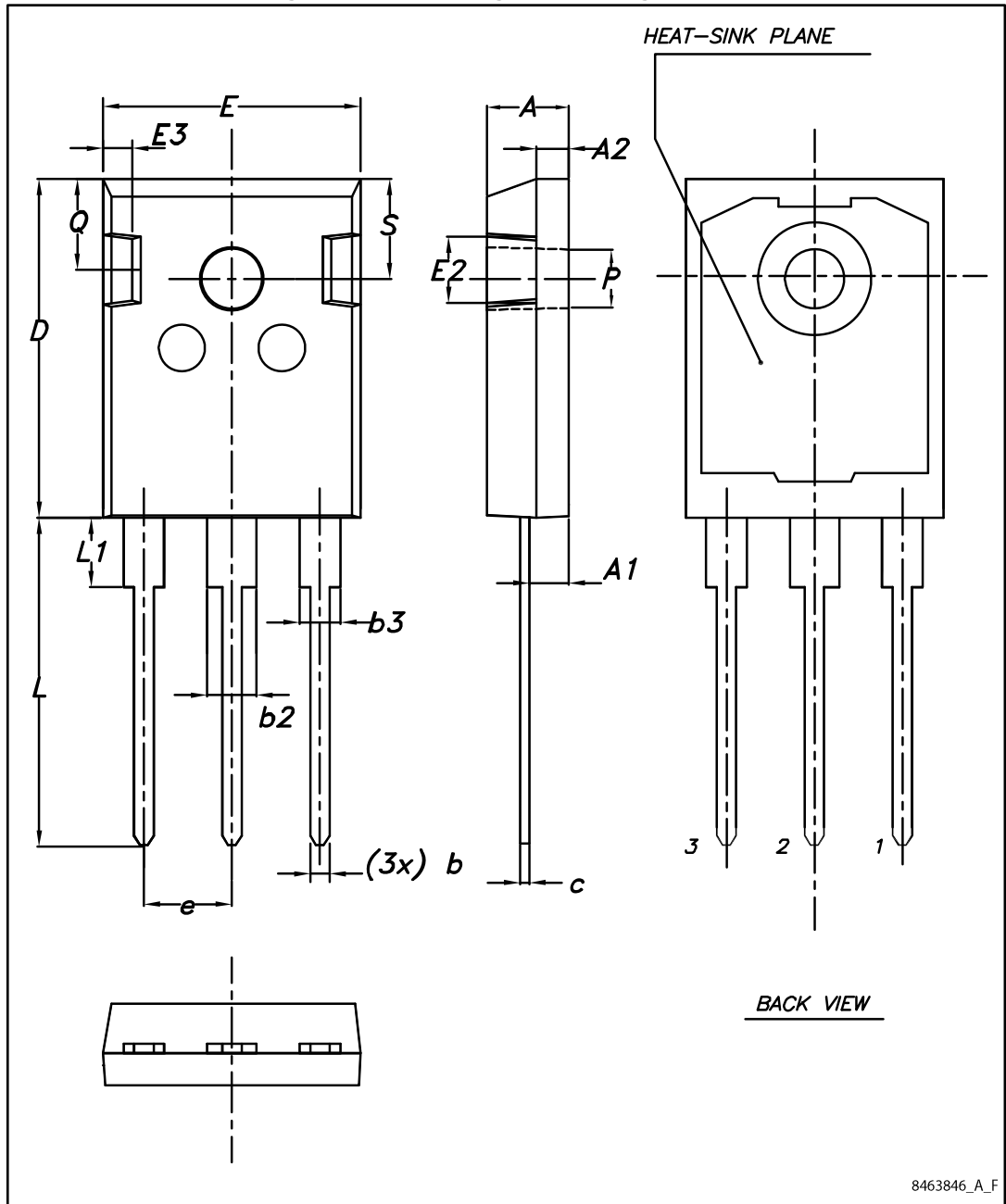


Table 9: TO-247 long leads package mechanical data

Dim.	mm.		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
c	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
P	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25

5 Revision history

Table 10: Document revision history

Date	Revision	Changes
04-May-2015	1	First release.
14-Sep-2015	2	Updated features in cover page and added new t_{sc} condition in Table 6: "IGBT switching characteristics (inductive load)" .
18-Dec-2015	3	Added part number STGW30M65DF2 Added Section 4.1: "TO-247 package information" Minor text changes.

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